

SPECIFICATION

1. PART NUMBER

Part Number	Packaging	Quantity
MM8430-2610B	Bulk Package	
MM8430-2610RA1	178 mm dia. reel	1000 pcs/reel
MM8430-2610RB3	330 mm dia. reel	3000 pcs/reel

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2. MECHANICAL

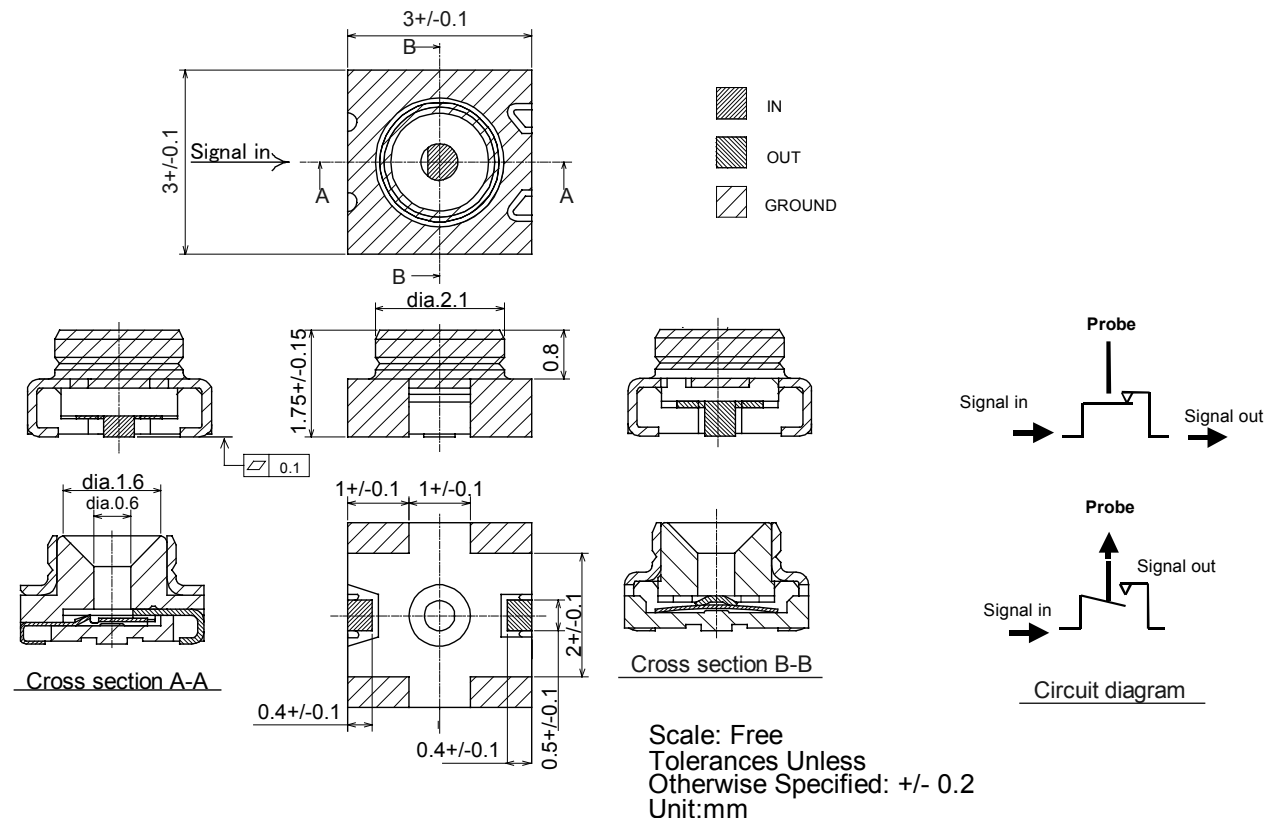
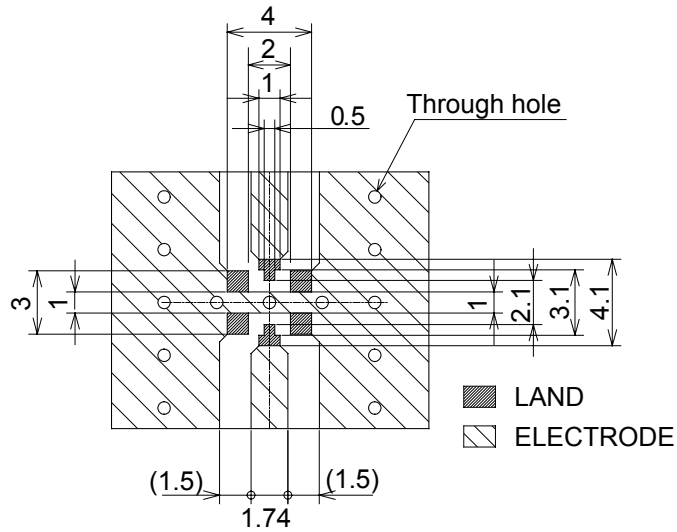


FIGURE1.Construction

3. RATING:

Item	Specification
Voltage Rating	250V r.m.s. maximum
Nominal Frequency Range	DC to 6GHz
Nominal Impedance	50Ω
D>Temperature Rating	-40°C to +90°C
Insulation Resistance	500 MΩ minimum
Withstanding Voltage	No evidence of breakdown
E>Initial Contact Resistance (without conductor resistance)	Center contact 50.0mΩmax. Outer contact 20.0mΩmax.
Voltage Standing Wave Ratio (V.S.W.R.)	Meet the requirements of following spec. 1.2 max. (DC to 3GHz) 1.3 max. (3GHz to 6GHz)
Insertion Loss	0.1dBmax. (DC~3GHz) 0.2dBmax.(3GHz ~6GHz)
Isolation	20dBmin.(DC~3GHz) 15dBmin.(3GHz ~6GHz)
Durability	500 cycles

4. STANDARD PATTERN DIMENSION



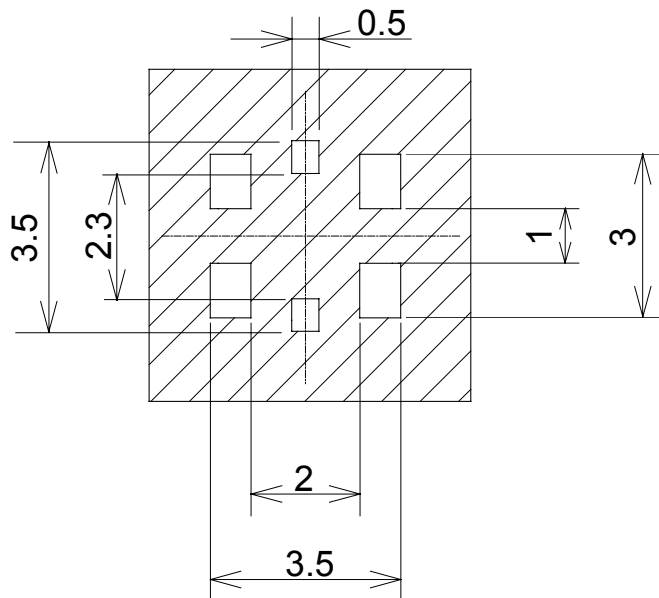
Unit: mm

- (Note) I/O pattern should be designed to be the impedance match 50 ohm.
 ·The material of PCB is the epoxy resin of glass fabric base. ($\epsilon_r=4.8$). Thickness is 1.0mm.
 ·The solder resist should be printed except for the land pattern on the PCB

FIGURE2. Standard pattern dimensions

5. STANDARD STENCIL MASK PATTERN

The standard stencil mask pattern is as FIGURE 3. (Thickness is 0.15mm)
 There is the possibility to have the contact failure by solder shifting into contact point, if the excess solder is used by non standard stencil mask pattern



Unit: mm

- The standard solder cream metal stencil mask drawing (Thickness 0.15mm)
 Note) There is the possibility to have the contact failure by solder shifting into contact point, if the excess solder is used by non standard stencil mask pattern.

FIGURE3. Standard stencil mask pattern